

MATERIALS CONTENT DECLARATION FORM SOT23 PACKAGE

PART NUMBER SUFFIX OPTION: "D"

PART NUMBER SUFFIX OPTION: "H" & "Q"

NOTE: EPOXY IS Pb-FREE, RoHS NON-GREEN, NON-HALOGEN FREE					
1 PC WT: 8.8494 mg					
COMPOSITION BREAKDOWN	M.U.M. (MAKE UP OF MATERIALS)	CHEMICAL COMPOSITION	CAS NO	CONTENT (IN %, TOTAL = 100%)	SUBSTANCE WEIGHT (IN mg)
LEADFRAME (2.714 mg)	ALLOY-42	IRON (Fe) NICKEL (Ni) COBALT (Co) COPPER (Cu) SILVER (Ag)	7439-89-6 7440-02-0 7440-48-4 7440-50-8 7440-22-4	20.9 9.0 0.1 0.0 0.7	1.8500 0.7929 0.0050 0.0020 0.0648
CHIP (0.0127 mg)	SILICON	SILICON (Si)	7440-21-3	0.1	0.0127
BONDING WIRE (0.038 mg)	COPPER	COPPER (Cu)	7440-50-8	0.4	0.0380
ENCAPSULATION (6.06 mg)	EPOXY RESIN	SILICON DIOXIDE (SiO2) EPOXY ANTIMONY TRIOXIDE (Sb2O3) BROMINATED EPOXY	60676-86-0 29690-82-2 1309-64-4 68928-70-1	48.0 18.5 1.0 1.0	4.2420 1.6360 0.0900 0.0900
TERMINATION PLATING (0.026 mg)	PURE TIN	TIN (Sn)	7440-31-5	0.3	0.0260

NOTE: EPOXY IS GREEN, HALOGEN FREE, Pb-FREE, RoHS					
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BONDING WIRE (0.038 mg)	COPPER	COPPER (Cu)	7440-50-8	0.4	0.0380
ENCAPSULATION (6.06 mg)	EPOXY RESIN	SILICON DIOXIDE (SiO2) EPOXY *PROPRIETARY FLAME RETARDANT	60676-86-0 29690-82-2 ---	48.0 18.5 2.0	4.2420 1.6360 0.1800
TERMINATION PLATING (0.026 mg)	PURE TIN	TIN (Sn)	7440-31-5	0.3	0.0260

* PROPRIETARY HYDROXIDE OF MAGNESIUM AND ALUMINUM.

			
TITLE SOT23 JUMPER ZERO OHM RESISTORS			
SCALE 1:1	SIZE A	DRAWING NO. 120023	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 1